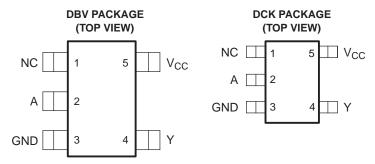


SINGLE SCHMITT-TRIGGER BUFFER

FEATURES

- Qualified for Automotive Applications
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V

- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This single Schmitt-trigger buffer is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G17-Q1 contains one buffer and performs the Boolean function Y = A. The device functions as an independent buffer, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION(1)

T _A	PACKAC	3E ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾
40°C to 125°C	SOT (SOT-23) - DBV	Reel of 3000	SN74LVC1G17QDBVRQ1	C17_
–40°C to 125°C	SOT (SC-70) - DCK	Reel of 3000	SN74LVC1G17QDCKRQ1	C7_

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) DBV/DCK: The actual top-side marking has one additional character that designates the wafer fab/assembly site.

FUNCTION TABLE

INPUT A	OUTPUT Y
Н	Н
L	L

LOGIC DIAGRAM (POSITIVE LOGIC)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	TYP MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6.5	V
V_{I}	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Voltage range applied to any output in the high	gh-impedance or power-off state ⁽²⁾	-0.5	6.5	V
Vo	Voltage range applied to any output in the hig	gh or low state (2) (3)	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current $V_1 < 0$ —50		-50	mA	
I _{OK}	Output clamp current V _O < 0			-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
0	Declines the world in a dame (4)	DBV package 2		206	°C/W
θ_{JA}	Package thermal impedance ⁽⁴⁾	DCK package		252	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- 3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT	
\/	Complexed to the	Operating	1.65	5.5	V	
V_{CC}	Supply voltage	Data retention only	1.5		V	
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	V _{CC}	V	
		V _{CC} = 1.65 V		-4		
	High-level output current	V _{CC} = 2.3 V		-8	mA	
I _{OH} High-level out		V 2V		-16		
		$V_{CC} = 3 V$		-24		
		V _{CC} = 4.5 V		-32		
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		8	mA	
I_{OL}	Low-level output current	V 2V		16		
		V _{CC} = 3 V		24		
		V _{CC} = 4.5 V		32		
		Human-Body Model		2 (H2)		
	ESD rating	Charged-Device Model		1 (C5)	kV	
		Machine Model		200 (M3)	V	
T _A	Operating free-air temperature		-40	125	°C	

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Submit Documentation Feedback



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

P	ARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹⁾	MAX	UNIT	
			1.65 V	0.64	1.25		
Positive-going			2.3 V	1	1.68		
V_{T+}	input threshold		3 V	1.36	2.04	V	
	voltage		4.5 V	2.07	2.86		
			5.5 V	2.53	3.43		
			1.65 V	0.23	0.71		
	Negative-going		2.3 V	0.44	1.05		
V_{T-}	input threshold		3 V	0.77	1.35	V	
	voltage		4.5 V	1.22	2.09		
			5.5 V	1.73	2.52		
			1.65 V	0.26	0.74		
			2.3 V	0.33	0.92		
ΔV_{T}	Hysteresis (V _{T+} – V _{T-})		3 V	0.4	0.99	V	
	(V + V -)		4.5 V	0.45	1.28		
			5.5 V	0.56	1.32		
		$I_{OH} = -100 \mu A$	1.65 V to 4.5 V	V _{CC} - 0.1			
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
.,		$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		.,	
V _{OH}		$I_{OH} = -16 \text{ mA}$ $I_{OH} = -24 \text{ mA}$		2.4		V	
				2.3		1	
		I _{OH} = -32 mA	4.5 V	3.8			
		I _{OL} = 100 μA	1.65 V to 4.5 V		0.1		
		I _{OL} = 4 mA	1.65 V		0.45		
.,		I _{OL} = 8 mA	2.3 V		0.4	.,	
V_{OL}		I _{OL} = 16 mA	2.1/		0.5	V	
		I _{OL} = 24 mA	3 V		0.7		
		I _{OL} = 32 mA	4.5 V		0.7		
I	A input	V _I = 5.5 or GND	0 to 5.5 V		±10	μΑ	
I _{off}	1	V_I or $V_O = 5.5 \text{ V}$	0		±25	μΑ	
I _{CC}		V _I = 5.5 V or GND, I _O = 0	1.65 V to 5.5 V		20	μΑ	
ΔI_{CC}		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V		500	μΑ	
Ci		V _I = V _{CC} or GND	3.3 V	4.5		pF	

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



Switching Characteristics

over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ or 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = ± 0.		V _{CC} = ± 0.		V _{CC} = ± 0.		UNIT
	(INFOT)	(1141 01)		MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	Α	Y	2.8	14	1	9	1.5	8	0.7	7	ns

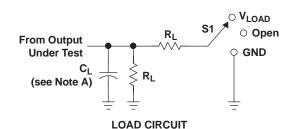
Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V	$V_{CC} = 2.5 V$	$V_{CC} = 3.3 \text{ V}$	$V_{CC} = 5 V$	UNIT
FARAMETER	TEST CONDITIONS	TYP	TYP	TYP	TYP	ONII
C _{pd} Power dissipaton capacitance	f = 10 MHz	20	21	22	26	pF

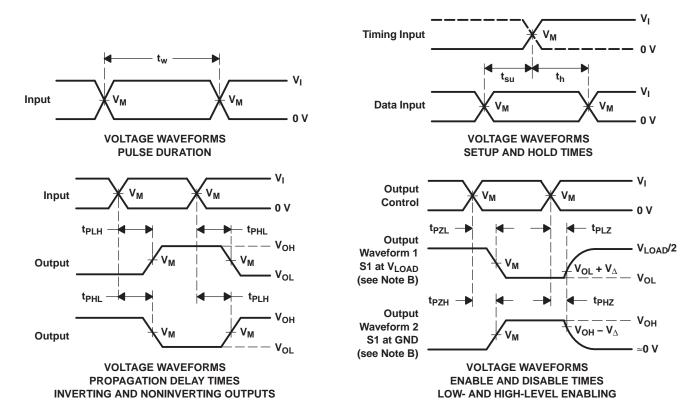


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V_{LOAD}
t _{PHZ} /t _{PZH}	GND

.,	INF	PUTS	.,	.,		_	.,
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	V_{Δ}
1.8 V ± 0.15 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	V _{CC}	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_0 = 50 Ω .
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





17-Nov-2008

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins P	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC1G17QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	Cu NiPdAu	Level-1-260C-UNLIM
SN74LVC1G17QDCKRQ1	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVC1G17-Q1:

Catalog: SN74LVC1G17

Enhanced Product: SN74LVC1G17-EP

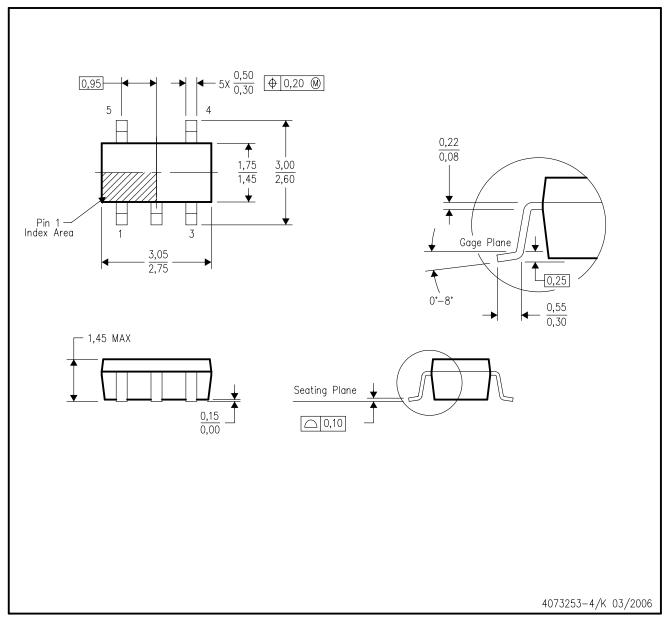
NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
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- D. Falls within JEDEC MO-203 variation AA.



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